ABSTRACT OF THE DISCLOSURE

A manufacturing method of forming at low costs a surface conduction electron-emitting device by which microminiaturization can be easily realized and electron-emitting characteristics which are uniform over a large area can be obtained is provided. A resin pattern with ion-exchange performance is formed on a substrate, a solution containing a metal component is absorbed to the resin pattern portion by using a deionization reaction, thereafter, the resin pattern is baked to thereby form an electroconductive thin film, and a forming operation is executed to the obtained electroconductive thin film, thereby manufacturing the surface conduction electron-emitting device.